



7360™

April 2008

## PRODUCT DESCRIPTION

7360™ provides the following product characteristics:

|                      |   |
|----------------------|---|
| <b>Technology</b>    | Solvent cleaner                         |
| <b>Chemical Type</b> | Aliphatic ester blend                   |
| <b>Appearance</b>    | Clear colorless solution <sup>LMS</sup> |
| <b>Viscosity</b>     | Very low                                |
| <b>Cure</b>          | Not applicable                          |
| <b>Application</b>   | Solvent for uncured SM adhesives        |

7360™ is a non-CFC, low odor, solvent based formulation intended for the removal of uncured adhesive and adhesive residues used in the PCB assembly industry. The solvent is fully compatible with epoxy adhesives and will not cause hardening during soaking. 7360™ is recommended for cleaning of stencils, screens and dispensing nozzles used to apply surface mount adhesives and for removal of adhesives from misprinted circuit boards.

## TYPICAL PROPERTIES

|                              |                            |
|------------------------------|----------------------------|
| Specific Gravity @ 25 °C     | 1.09                       |
| Infrared Spectrum            | As standard <sup>LMS</sup> |
| Viscosity @ 20°C, mPa·s (cP) | 2.5                        |
| TLV (ACGIH), ppm             | 100                        |
| Flash Point - See MSDS       |                            |

## TYPICAL PERFORMANCE

7360™ has no effect on the speed of cure or final strength of LOCTITE® adhesives other than providing a clean surface for good adhesion and adhesive cure. Unclean or partially cleaned surfaces can affect adhesive performance. The solvent is fully compatible with commonly used solder resists.

## GENERAL INFORMATION

**This product is not recommended for use in pure oxygen and/or oxygen rich systems and should not be selected with a sealant for chlorine or other strong oxidizing materials.**

**For safe handling information on this product, consult the Material Safety Data Sheet (MSDS).**

## Directions for use:

It is advisable to use protective clothing to avoid contact with the solvent and adhesive. The low volatility of this solvent makes it ideal for open reservoirs but does mean that it requires drying by cloth or compressed air.

**Cleaning Dispenser Needles & Components** - using spray can with extension tube and tip

1. The simplest and most effective cleaning is to "jet spray" the uncured adhesive out of the needle bore by ensuring a snug fit between the tip on the extension tube and the

needle. (The tip can be cut to suit different needle types)

2. Dry out needle by blowing through bore using dry compressed air.
3. Check for cleanliness and that no blockage remains.

## Using Ultrasonic or Static Bath

1. Uncured adhesive should be mechanically removed as much as possible by using a blunt tool for any larger cavities and a drill bit or piano wire of appropriate diameter for the needle bore. This operation helps minimize solvent usage.
2. Immerse items to be cleaned in a reservoir of fresh solvent.
3. If using an ultrasonic bath, set at maximum power for 3 minutes at 40 °C.
4. If using a static bath, use tweezers to agitate the items in the bath until solvent has become stained due to removal of adhesive. Rinse in fresh solvent to confirm cleanliness.
5. For needles with very small bores or cavities it is recommended to follow with a "jet spray" clean as previously described.
6. Dry out parts and blow through bore using dry compressed air.

## Cleaning Boards, Stencils, Wiper Blades

1. Apply solvent direct from can to dry lint free cloth, or spray directly onto adhesive on surface to be cleaned.
2. Wipe away uncured adhesive (one wipe is usually sufficient).
3. Dry surface with a clean dry cloth.

## Note:

- All dispensing parts being cleaned may be left to soak for several days without risk of hardening the adhesive or adversely affecting the material being cleaned.
- While the solvent has been checked for compatibility with materials commonly used in PCB assembly, certain plastics or coatings may be affected and should be checked for compatibility before use.
- Needle blockages due to cured or partially cured adhesive should be cleared using a drill bit before solvent cleaning.

## Loctite Material Specification<sup>LMS</sup>

LMS dated December 01, 2004. Test reports for each batch are available for the indicated properties. LMS test reports include selected QC test parameters considered appropriate to specifications for customer use. Additionally, comprehensive controls are in place to assure product quality and consistency. Special customer specification requirements may be coordinated through Henkel Quality.



**Storage**

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

**Optimal Storage: 8 °C to 21 °C. Storage below 8 °C or greater than 28 °C can adversely affect product properties.**

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

**Note**

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Reference 1.1